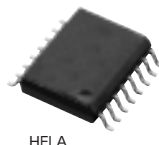


MONOLITHIC AMPLIFIERS

50&75Ω

High IP3 5 to 1000 MHz



HELA

All specifications at 25°C

KIT NO.	APPLICATION CIRCUIT	FREQ. ² (MHz) f _i - f _o	OHMS	GAIN ¹ (dB)				MAXIMUM POWER (dBm)			DYNAMIC RANGE		VSWR ² (:1) Typ.		DC POWER		THERMAL RESIS- TANCE ³ qjc °C/W	CASE STYLE Note B	CON- NECTION	PRICE
				Min.	Typ.	Max.	Typ. Flatness	Output (1 dB Comp.) Typ.	Input (no damage)	NF (dB) Typ.	IP3 (dBm) Typ.	In	Out	Volt Typ.	Current (mA)	Qty. (1-9)				\$
HELA-10A	A	50 - 1000	75	10.0	12.0	13.0	±0.4	30	26	20	3.5	47	1.22	1.22	12	525	6	CM624	kl	19.95
HELA-10B	B	50 - 1000	50	10.0★	12.0	13.0	±0.4	30	26	20	3.5	47	1.22	1.22	12	525	6	CM624	kl	19.95
HELA-10C	C	5 - 450	75	9.3	11.4	12.5	±0.4	30	26	20	3.5	48	1.30	1.22	12	525	6	CM624	kl	19.95
HELA-10D	D	8 - 300	50	9.3	11.0	12.5	±0.4	30	26	20	3.5	48	1.20	1.20	12	525	6	CM624	kl	19.95

♦ Kit consists of HELA-10 plus transformers, see table below.

see suggested PCB layout PL-076 for HELA models

features

- very high IP3, 49 dBm typ at 150 MHz & 45 dBm typ at 800 MHz
- excellent flatness, ±0.4 dB typ.
- very high IP2, 88 dBm typ.
- low noise figure, 3.5 dB typ.

applications

- cellular
- instrumentation
- CATV

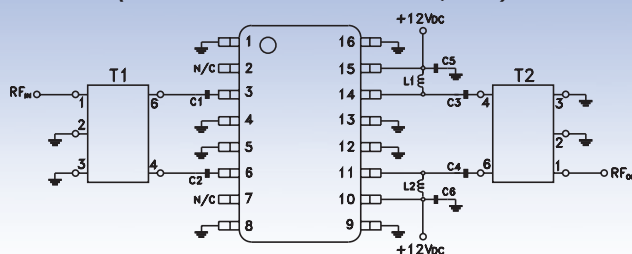
absolute maximum ratings

heat slug temperature: 110°C max.
storage temperature: -40°C to 150°C
dc voltage: 13V
dc power: 7.15W

NOTES:

- ♦ Aqueous washable
- ★ 9.5 dB min., 800-1000 MHz.
- ⊗ Tested with recommended application schematic diagram.
- A. Environmental specifications and re-flow soldering information available in General Information Section.
- B. Units are non-hermetic unless otherwise noted. For details on case dimensions & finishes see "Case Styles & Outline Drawings".
- C. Prices and Specifications subject to change without notice.
- D. For Quality Control Procedures see Table of Contents, Section 0, "Mini-Circuits Guarantees Quality" article. For Environmental Specifications see Amplifier Selection Guide.
- 1. Includes transformer losses at input & output.
- 2. HELA Series, VSWR for 75 ohm. For 50 ohm, VSWR increases from 1.2:1 at 1 GHz to 2.0:1 at 500 MHz.
- 3. Thermal resistance is from junction to heat slug, or mounting paddle.
- 4. Open load is not recommended, potentially can cause damage. With no load, derate max input power by 20 dB.

application schematic diagram (see table below for values C1 to C6, L1&L2)



APPLICATION CIRCUIT	T1	T2	C1 TO C6	L1,L2	PCB LAYOUT	EVALUATION BOARD
A	ADTL1-18-75	ADTL1-18-75	0.01μF	0.75μH	B14-TB-30	TB-16
B	ADTL1-12	ADTL1-12	0.01μF	0.75μH	B14-TB-17	TB-17
C	ADT1-1WT	ADTL1-4-75	0.039μF	3.3μH	B14-TB-16	TB-30
D	ADT1-5-1	ADT1-5-1	0.039μF	3.3μH	B14-TB-17	TB-45

Assembly Guideline

Reflow solder the slug to the ground plane; PC board layouts for 75 ohm (B14-TB-16), (B14-TB-30) and for 50 ohm (B14-TB-17) are available upon request. Please contact Applications Department or consult our website.

pin connections

PORT	kl
RF IN	3,6
RF OUT	11,14
DC	10,15
GND EXT.	1,4,5,8,9,12,13,16
NOT USED	2,7



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